

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
 Contact Info: ti.com/support
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
 Created on: 06/05/2022

Details for "SN65LBC176QDRG4"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
SN65LBC176QDRG4	NIPDAU	Level-1-260C-UNLIM	TI TAIWAN A/T	D 8	3.91x4.9x1.58	82.5

*Total Device Mass
 The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Other Nonferrous Metals and Alloys	Yttrium	7440-65-5	0.000001	0.001144	11	0.000001	0
Precious Metals	Gold	7440-57-5	0.087441	99.997713	999977	0.105939	1059
Precious Metals	Silver	7440-22-4	0.000001	0.001144	11	0.000001	0
Sub-Total			0.087443	100	1000000	0.105942	1059
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.454412	70	700000	0.550544	5505
Thermoplastics	Epoxy	85954-11-6	0.194748	30	300000	0.235947	2359
Sub-Total			0.64916	100	1000000	0.786491	7865
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	24.25509	97.41	974100	29.386299	293863
Copper and Its Alloys	Iron	7439-89-6	0.5976	2.4	24000	0.724023	7240
Copper and Its Alloys	Phosphorus	7723-14-0	0.00747	0.03	300	0.00905	91
Other Nonferrous Metals and Alloys	Lead	7439-92-1	0.00747	0.03	300	0.00905	91
Other Nonferrous Metals and Alloys	Tin	7440-31-5	0.00747	0.03	300	0.00905	91
Zinc and Its Alloys	Zinc	7440-66-6	0.0249	0.1	1000	0.030168	302
Sub-Total			24.9	100	1000000	30.16764	301676
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	0.355273	95.119946	951199	0.430432	4304
Precious Metals	Gold	7440-57-5	0.002913	0.77992	7799	0.003529	35
Precious Metals	Palladium	7440-05-3	0.015314	4.100134	41001	0.018554	186
Sub-Total			0.3735	100	1000000	0.452515	4525
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	40.918797	76.000001	760000	49.575243	495752
Other Organic Materials	Proprietary Non Halide Flame Retardant	Trade Secret	1.884418	3.499999	35000	2.28307	22831
Other Plastics and Rubber	Carbon Black	1333-86-4	0.161522	0.300001	3000	0.195692	1957
Thermoplastics	Epoxy	85954-11-6	10.875785	20.199999	202000	13.176577	131766
Sub-Total			53.840522	100	1000000	65.230583	652306
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	2.688147	100	1000000	3.256829	32568
Sub-Total			2.688147	100	1000000	3.256829	32568
Total			82.538772			100	1000000

Important Note
 The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.
 The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component.
[See Glossary of Terms for more details.](#)

Important Part Information
 There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSLs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology
[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."
[For additional information, please contact TI customer support.](#)

Signature: [\(click here for a fuller statement with a signed certificate\)](#)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality
 For further environmental statements, please go to www.ti.com/ecoinfo
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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet J5709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.